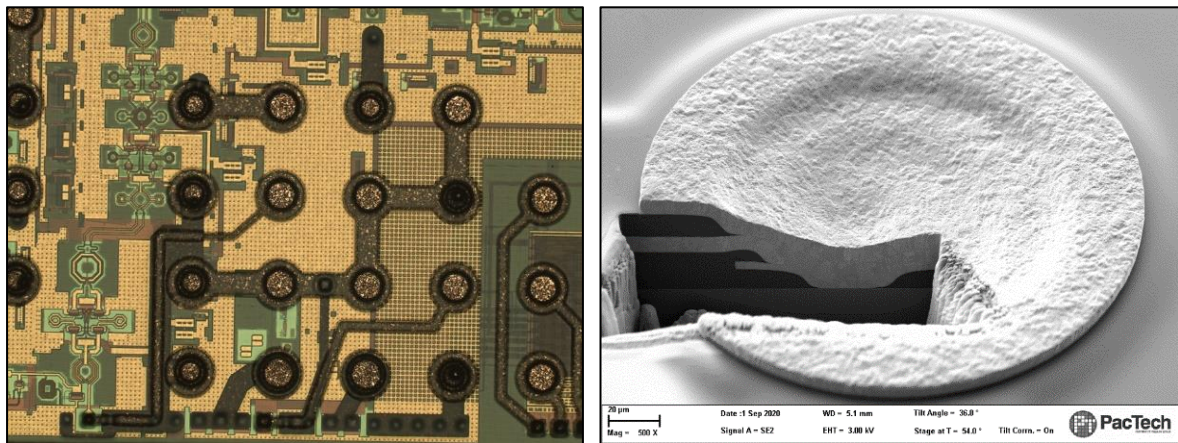


PacTech Expands Technology Portfolios in Wafer Level Packaging Services

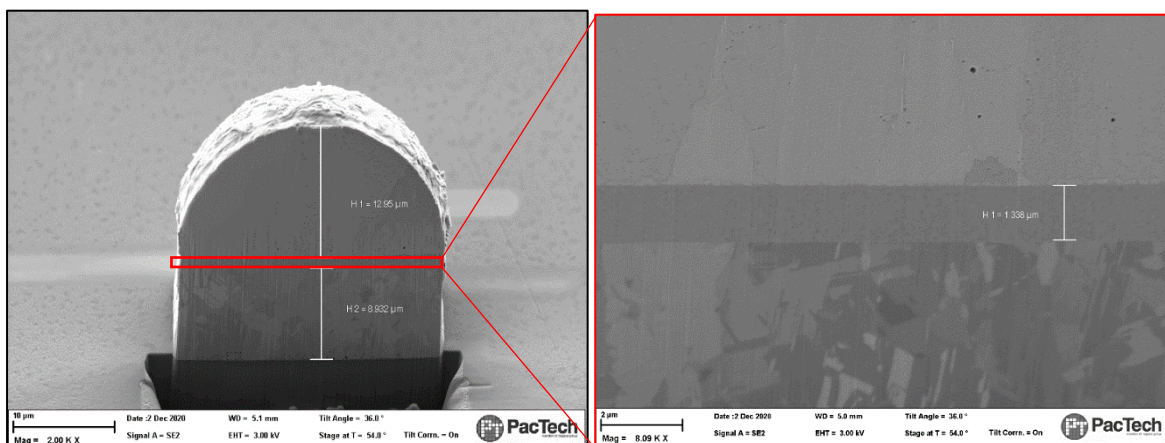
With three manufacturing sites located across continents, PacTech is producing over 30,000 wafers per month for various applications including consumers, industrial, RF, automotive, aerospace and more. PacTech has added additional capabilities and process know-hows in the array of Wafer Level Packaging Services following the market trend of “More than Moore”, enabling multi-layer, fine pitch, high density and high-performance technologies.

PacTech, as a pioneer in electroless plating, has been expanding the technology horizontally with additional metallization finish of Ag, Cu and Sn; while qualifying the technology vertically into various emerging alternatives to standard Silicon wafers, such as SiGe, LiTaO₃, GaN, SiC and Glass wafers.

Furthermore, various multi-layer RDL and Cu pillar finishes in combination of various metallization technologies including industrial standard finishes as well as PacTech’s unique innovations are available in PacTech to cater to all kinds of applications and performances.



Multi-layer Cu RDL for Si and Glass



Electroplated CuNiSnAg Pillar Interconnection or UBM for Solder Ball Attach



Chemically activated electroless Cu seed layer
for Cu plating on Glass and Polymers including
Via Formation

Dec. 10, 2020